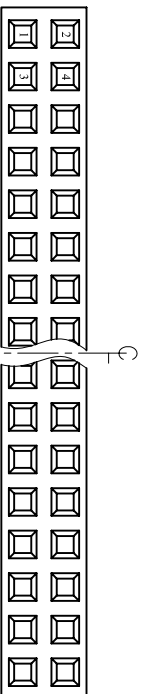


HSP

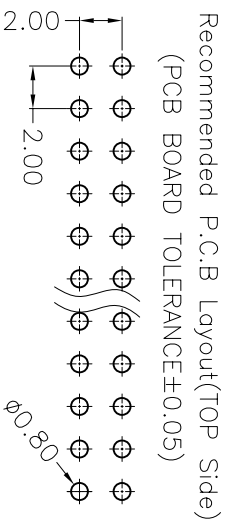
NOTES:

Current Rating: 2.0AMP
 Withstand Voltage: 500V AC/DC
 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩMin
 Operation Temperature: -40°C to +105°C

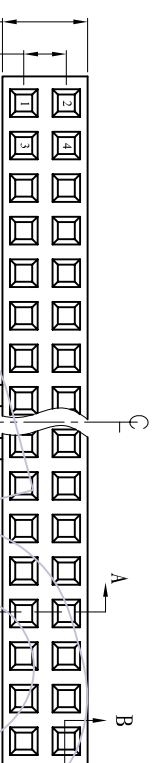
Contact Material: Phosphor Bronze
 Contact plating: Au or Sn over Ni
 Insulator Material: PA6T+30%G, F UL94V-0



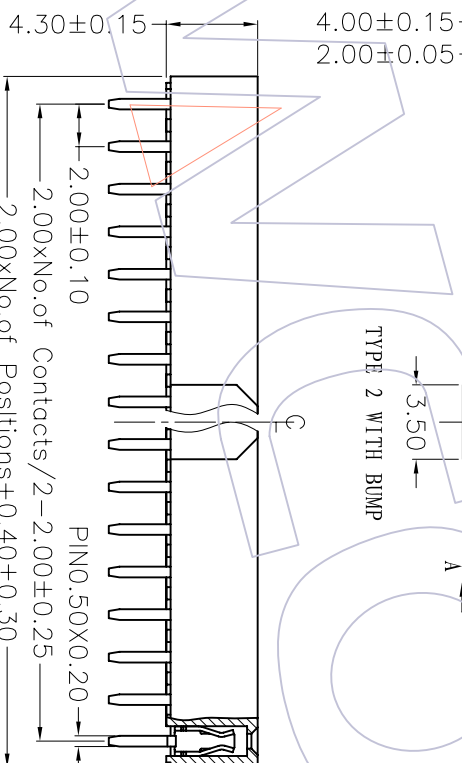
TYPE 1 W/O BUMP



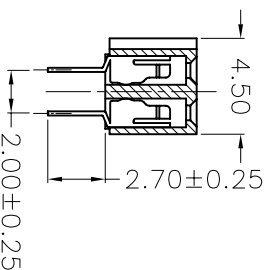
Recommended P.C.B Layout(TOP Side)
 (PCB BOARD TOLERANCE±0.05)



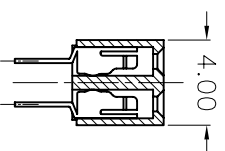
TYPE 2 WITH BUMP



SECTION B-B



TYPE 2 WITH BUMP



TYPE 1 W/O BUMP

Ordering Information

2243N - 2 XX S XX CUNT X

No. of Pins per ROW: 02~40Pin
 Contact Plating: Gold Flash
 GH=3µ"Gold
 GS=5µ"Gold
 GS=10µ"Gold
 GS=30µ"Gold
 SO=Gold Flash/Tin
 SI=3µ"Gold/Tin
 S2=5µ"Gold/Tin
 S3=10µ"Gold/Tin
 S4=5µ"Gold/Tin
 S5=30µ"Gold/Tin
 SN=Tin

Packing:
 T=Tube
 P=Tube+CAP
 R=Tray&Reel+CAP

Series No.
 1=TYPE 1
 2=TYPE 2

SECTION A-A

TYPE	PART NO.
TYPE 1	2243N-2XXSXXCUNT1
TYPE 2	2243N-2XXSXXCUNT2

WCON 维峰五金电子有限公司
 WAFER HARDWARE ELECTRONICS CO., LTD

SEE TABLE

FH2.00mm Dia L 180° H=4.3 W=4.0

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO	08/02/28	NEW		

OPERATION	DRAW	SCALE
X.X	MeiLiq	3:1
X.XX	DESIGN	UNIT
X.XXX	CHECK	SIZE
Angle	APPROVE	SHEET
± 3'		1/1
± 0.15		PROJ.
± 0.25		Customer NO.

OPERATION	DRAW	SCALE	PART NO.
X.X	MeiLiq	3:1	
X.XX	DESIGN	UNIT	
X.XXX	CHECK	SIZE	
Angle	APPROVE	SHEET	
± 3'		1/1	
± 0.15		PROJ.	
± 0.25		Customer NO.	

1 2 3 4 5 6 7 8 9 10